## 12 TO 36 MHZ 6TSOT VCXO

#### DATASHEET

#### ICS726A

#### Description

Used in conjunction with an external pullable quartz crystal, this monolithic integrated circuit replaces more costly hybrid (canned) VCXO devices. The ICS726A is designed primarily for data and clock recovery applications such as ADSL modems, set-top box receivers, and telecom systems.

The frequency of the on-chip VCXO is adjusted by an external control voltage to the VIN pin. Since VIN is a high impedance input, it can be driven directly from an PWM RC integrator circuit. Frequency output increases with VIN voltage input. The usable range of VIN is 0 to 3.3 V.

#### **Features**

- Uses an inexpensive 12 to 36 MHz external crystal
- Output frequency range of 12 to 36 MHz
- On-chip VCXO with guaranteed pull range of ±115 ppm minimum
- VCXO tuning voltage 0 to 3.3 V
- Packaged in 6-pin TSOT
- Pb (lead) free package



#### **Block Diagram**

#### **Pin Assignment**



### **Pin Descriptions**

Pin Number	Pin Name	Pin Type	Pin Description
1	X2	Input	Crystal connection. Connect to the external pullable crystal.
2	GND	Power	Connect to ground.
3	CLK	Output	VCXO CMOS level clock output at the frequency of the crystal.
4	VDD	Power	Connect to +3.3 V (0.01µf decoupling capacitor recommended).
5	VIN	Input	Voltage input to VCXO — 0 to 3.3 V analog input which controls the oscillation frequency of the VCXO.
6	XI	Input	Crystal connection. Connect to the external pullable crystal.

## **External Component Selection**

The ICS726A requires a minimum number of external components for proper operation.

#### **Decoupling Capacitor**

A decoupling capacitor of  $0.01\mu$ F must be connected between VDD (pin 4) and GND (pin 2), as close to these pins as possible. For optimum device performance, the decoupling capacitor should be mounted on the component side of the PCB. Avoid the use of vias in the decoupling circuit.

#### **Series Termination Resistor**

When the PCB trace between the clock output (CLK, pin 3) and the load is over 1 inch, series termination should be used. To series terminate a  $50\Omega$  trace (a commonly used trace impedance) place a  $33\Omega$  resistor in series with the clock line, as close to the clock output pin as possible. The nominal impedance of the clock output is  $20\Omega$ 

#### **Quartz Crystal**

The ICS726A VCXO function consists of the external crystal and the integrated VCXO oscillator circuit. To assure the best system performance (frequency pull range) and reliability, a crystal device with the recommended parameters (shown below) must be used, and the layout guidelines discussed in the following section shown must be followed.

The frequency of oscillation of a quartz crystal is determined by its "cut" and by the load capacitors connected to it. The ICS726A incorporates on-chip variable load capacitors that "pull" (change) the frequency of the crystal. The crystal specified for use with the ICS726A is designed to have zero frequency error when the total of on-chip + stray capacitance is 8.9 pF.

#### **Required Crystal Parameters:**

Nominal Frequency	as required MHz
Initial Accuracy at 25°C	-20 min/+20 max ppm
Temperature Stability	-30 min/+30 max ppm
Aging, 1st year	-5 min/+5 max ppm
Aging, 10 years	-20 min/+20 max ppm
Operating Temp. Range, °C	0 min/+25 typ/+70 max
or Operating Temp. Range, °C Load Capacitance Shunt Capacitance, C0 C0/C1 Ratio Equivalent Series Resistance	-40 min/+25 typ/+85 max 8.6 pf 7 pF Max 270 Max 35 Ω Max

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The third overtone mode of the crystal and all spurs must be >100 ppm distant from the 3x fundamental resonance measured with a physical load of 8.6pF.

The external crystal must be connected as close to the chip as possible and should be on the same side of the PCB as the ICS726A. There should be no vias between the crystal pins and the X1 and X2 device pins. There should be no signal traces underneath or close to the crystal. See application note MAN05.

#### **Crystal Tuning Load Capacitors**

The crystal traces should include pads for small fixed capacitors, one between X1 and ground, and another between X2 and ground. The need for these capacitors is determined at system prototype evaluation, and is influenced by the particular crystal used (manufacture and frequency) and by PCB layout. The typical required capacitor value is 1 to 4 pF.

To determine the value of the crystal capacitors:

1. Connect VDD of the ICS726A to 3.3 V. Connect pin 5of the ICS726A to the second power supply. Adjust thevoltage on pin 5 to 0V. Measure and record the frequency of the CLK output. ( $f_{0V}$ )

2. Adjust the voltage on pin 5 to 3.3 V. Measure and record the frequency of the same output. ( $f_{high}$ )

To calculate the centering error:

Centering error

= 
$$10^{6} \cdot \frac{(f_{high} - f_{target}) + (f_{0v} - f_{target})}{2 \times f_{target}} - error_{xtal}$$

Where:

ftarget = nominal crystal frequency

 $Error_{xtal} = actual initial accuracy (in ppm) of the crystal being measured.$ 

If the centering error is less than  $\pm 25$  ppm, no adjustment is needed. If the centering error is more than 25 ppm negative, the PC board has excessive stray capacitance and a new PCB layout should be considered to reduce stray capacitance. (Alternately, the crystal may be re-specified to a higher load capacitance. Contact IDT for details.) If the centering error is more than 25 ppm positive, add identical fixed centering capacitors from each crystal pin to ground. The value for each of these caps (in pF) is given by:

= 2 x (centering error)/ (trim sensitivity)

Trim sensitivity is a parameter which can be supplied by your crystal vendor or calculated using the following formula:

trim sensitivity= 
$$\frac{10^8 \times C_1}{2 \times (C_0 + C_1)^2}$$

## **Absolute Maximum Ratings**

Stresses above the ratings listed below can cause permanent damage to the ICS726A. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

Item	Rating
Supply Voltage, VDD	7 V
All Inputs and Outputs	-0.5 V to VDD+0.5 V
Ambient Operating Temperature	0 to +70° C
Storage Temperature	-65 to +150° C
Soldering Temperature	260° C

### **Recommended Operating Conditions**

Parameter	Min.	Тур.	Max.	Units
Ambient Operating Temperature	0		+70	°C
Power Supply Voltage (measured in respect to GND)	+3.15		+3.45	V
Reference crystal parameters		Refer to	page 3	

## **DC Electrical Characteristics**

VDD = 3.3 V ±5%	, Ambient temperature	0 to +70° C, unles	s stated otherwise
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Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Operating Voltage	VDD		3.15		3.45	V
Output High Voltage	V <sub>OH</sub>	I <sub>OH</sub> = -12 mA	2.4			V
Output Low Voltage	V <sub>OL</sub>	I <sub>OL</sub> = 12 mA			0.4	V
Output High Voltage (CMOS Level)	V <sub>OH</sub>	I <sub>OH</sub> = -4 mA	VDD-0.4			V
Operating Supply Current	IDD	Output = 12 MHz, no load		5		mA
Short Circuit Current	I <sub>OS</sub>			±50		mA
VIN, VCXO Control Voltage	V <sub>IA</sub>		0		3.3	V

# AC Electrical Characteristics

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Output Frequency	F <sub>O</sub>		12		36	MHz
Crystal Pullability, Note 2	F <sub>P</sub>	$0V \le VIN \le 3.3 V$ , Note 1	±115			ppm
VCXO Gain		$VIN = VDD/2 \pm 1 V$ , Note 1		140		ppm/V
Output Rise Time	t <sub>OR</sub>	0.8 to 2.0 V, C <sub>L</sub> =15 pF		0.8	1.5	ns
Output Fall Time	t <sub>OF</sub>	2.0 to 0.8 V, C <sub>L</sub> =15 pF		0.8	1.5	ns
Output Clock Duty Cycle	t <sub>D</sub>	Measured at 1.4 V, $C_L$ =15 pF	40	50	60	%
Maximum Output Jitter, short term	tj	C <sub>L</sub> =15 pF		100		ps

VDD = 3.3 V ±5%, Ambient Temperature 0 to +70° C, unless stated otherwise

Note 1: External crystal device must conform with Pullable Crystal Specifications listed on page 3.

### Marking Diagram



Notes:

- 1. '26AL' denotes part number.
- 2. "L" denotes Pb (lead) free package.
- 3. Bottom marking: '####' denotes last 4 digits of lot number

## Package Outline and Package Dimensions (6-pin TSOT)

Package dimensions are kept current with JEDEC Publication No. 95



	Millimeters				
Symbol	Min	Max			
А	_	1.00			
A1	0.01	0.10			
A2	0.84	0.90			
b	0.30	0.45			
С	0.12 0.20				
D	2.90 BASIC				
Е	2.80 BASIC				
E1	1.60 BASIC				
е	0.95 E	BASIC			
e1	1.90 E	BASIC			
L	0.30 0.50				
L1	0.60 REF.				
L2	0.25 BASIC				
θ	<b>0</b> °	<b>8</b> °			
aaa	— 0.10				

## **Ordering Information**

Part / Order Number	Marking	Shipping Packaging	Package	Temperature
726ATLFT	26AL	Tape and Reel	6-pin TSOT	0 to +70° C

#### "A" denotes revision designator (will not corrrelate with datasheet revision)

#### "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

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